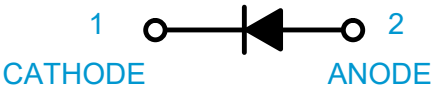
Features

- High Speed Switching
- Low IR
- Surface Device Type Mounting
- Ultra Small SMD Package
- RoHS Compliant

DFN1006-2L (Bottom View)

Applications

- Inverse-polarity protection
- Portable Applications i.e. PDA, Cell Phone, etc.



Order information

Device	Marking	Shipping
1N4148MD	S3	10,000/Tape &Reel

Absolute Maximum Ratings

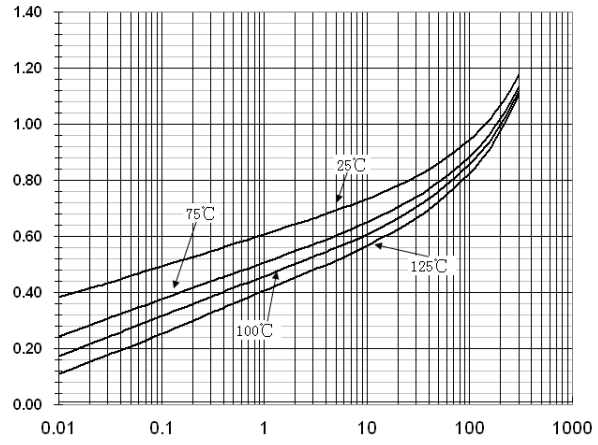
Parameter	Symbol	Limits	Unit
Repetitive Peak Reverse Voltage	VRRM	100	V
Maximum Average Forward Current	IF	150	mA
Forward Surge Current @1uS	IFSM	2	A
Storage Temperature	TSTG	-55~+125	℃
Operating Junction Temperature	TJ,TSTG	-55~+125	℃
Lead Temperature for Soldering Purposes (1/8″ from case for 10 s)	TL	260	℃
Junction−to−Ambient − Steady State (Note 1)	RθJA	520	℃/W

Note 1:
Surface−mounted on FR4 board using 1 inchsquarepad size (Cu area = 1.127 inch square [1 oz] including traces)

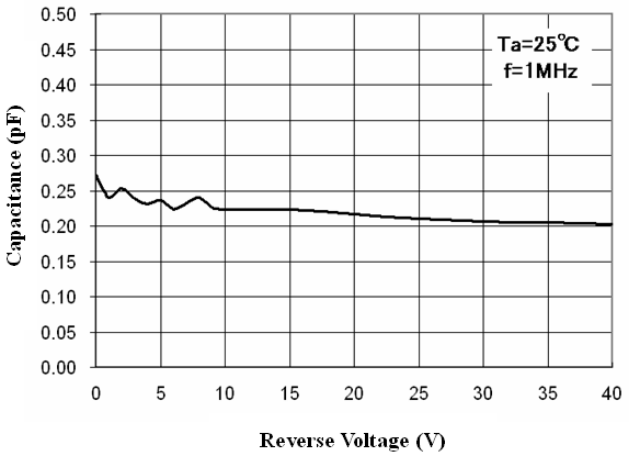
Electrical Characteristic (Ta= 25ºC)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Break Down Voltage (IR=100uA) (IR=5uA)	Vbr	100 75		-	V
Reverse Leakage Current (VR=20V) (VR=75V)	IR			0.025 5	μA
Forward Voltage (IF=10mA)	VF			1	V
Reverse Recovery Time (IF=10mA, IR=60mA, RL=100W, IRR=1mA)	Trr			4	nS
Capacitance (VR=0V, f=1MHZ)	Cj			4	pF

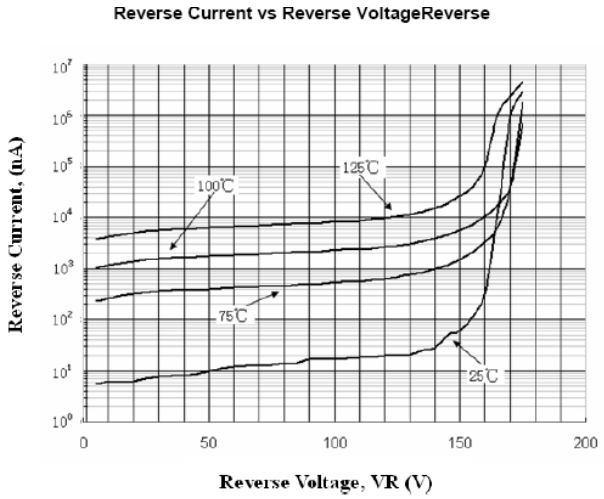
Characteristic Curves



F1. Forward Voltage vs Ambient Temperature

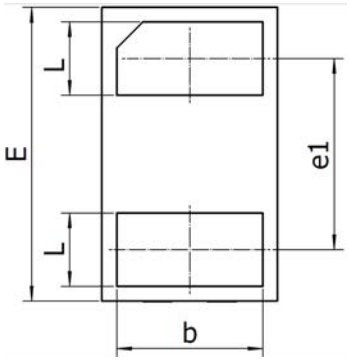


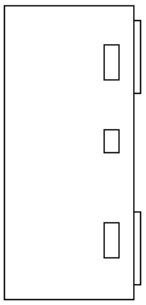
F2. Total Capacitance

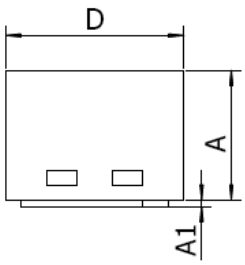


F3. Reverse Current vs Ambient Temperature

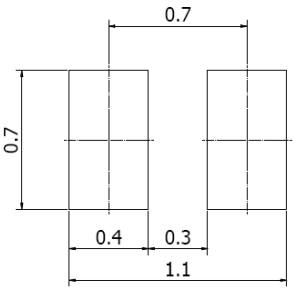
Outline and Dimensions







Typical Soldering Pattern(mm):



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.46	0.50	0.018	0.020
A1	---	0.03	---	0.001
b	0.45	0.55	0.018	0.022
D	0.55	0.65	0.022	0.026
E	0.95	1.05	0.037	0.041
e1	Typ. 0.65		Typ. 0.026	
L	0.20	0.30	0.008	0.012